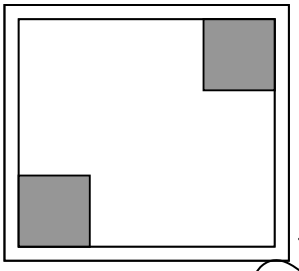
SiliconApps

Mega Ohm Thin Film Resistor Series

SiliconApps TM series resistor networks offer Mega Ohms resistors in a small print using thin film technology. TM Series 42X52 mil resistor chips are available in resistance values from 0.1 Mega ohms to 100 Mega Ohms.

Electrical Specifications			
Parameter	**Conditions**		
Temperature Coefficient of Resistance	-55°C to 125°C	±200ppm/°C	Max
Operating Voltage	-55°C to 125°C	100Vdc	Max
Power Rating (per resistor)	@ 70°C (Derate linearly to zero @ 150°C)	250mw	Max
Thermal Shock	Method 107 MIL-STD-202F	±0.5% @ΔR	Max
High Temperature Exposure	100 Hrs @ 150°C Ambient	±0.25% ΔR	Max
Moisture Resistance	Method 106 MIL-STD-202F	±0.5% ΔR	Max
Life	Method 108 MIL-STD-202F (125°C/1000 hr)	±0.5% ΔR	Max
Noise	Method 308 MIL-STD-202F upto 250 KΩ ≥250 KΩ	-35dB -20dB	Max
Insulation Resistance	@ 25°C	$1 \times 10^{12}\Omega$	Min

Mechanical Specifications	
Substrate	Silicon 10±2 mils thick
Isolation Layer	SiO_2 10,000Å thick, min
Backing	Lapped (gold optional)
Metalization	Aluminium 10,000Å thick, min (15,000Å gold optional)



0.1 mega Ohm to 100 mega

Bonding Pad area

Bonding pad size 4.0milsX4.0 mils.
Die Size 42milsX52mils.

Notes
1. Resistor pattern may vary from one value to another.

Part Number Designation					
TM	**1004**	**F**	**A**	**G**	**W**
Series	Value	Tolerance*	TCR	Bond Pads	Backing
	First 3 digits are	F = ±1%	No letter = ±200ppm>10Ω	G = Gold	W = Gold
	significant value.	G = ±2%	A = 150 ppm	No Letter = Aluminium	L = Lapped
	Last digit	J = ±5%			T = on mylar (diced)
	represents	K = ±10%			
	number of zeros.	M = ±20%			
	R indicates				
	decimal point.				

Notes:
Product can be shipped in as a wafer, diced on tape, or as chips in waffle packs.
Other resistor values are available upon request.